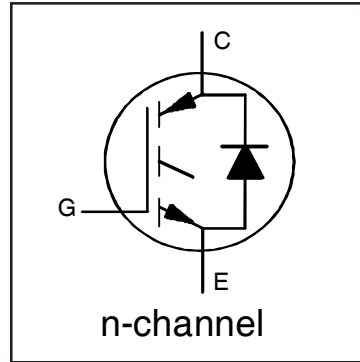


**INSULATED GATE BIPOLAR TRANSISTOR WITH ULTRA-LOW V_F DIODE
FOR INDUCTION HEATING AND SOFT SWITCHING APPLICATIONS**

Features

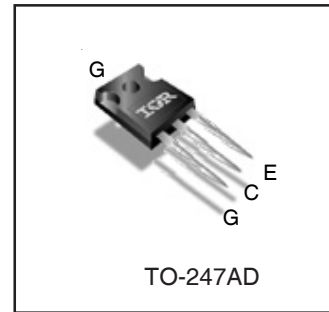
- Low V_{CE(ON)} trench IGBT technology
- Low switching losses
- Square RBSOA
- Ultra-low V_F Diode
- 1300Vpk repetitive transient capacity
- 100% of the parts tested for I_{LM} ①
- Positive V_{CE(ON)} temperature co-efficient
- Tight parameter distribution
- Lead free package



| |
|--|
| V _{CES} = 1200V |
| I _C = 45A, T _C = 100°C |
| T _{J(max)} = 150°C |
| V _{CE(on)} typ. = 1.7V @ I _C = 30A |

Benefits

- Device optimized for induction heating and soft switching applications
- High Efficiency due to Low V_{CE(on)}, low switching losses and Ultra-low V_F
- Rugged transient performance for increased reliability
- Excellent current sharing in parallel operation
- Low EMI



| | | |
|----------|-----------|----------|
| G | C | E |
| Gate | Collector | Emitter |

| Base part number | Package Type | Standard Pack | | Orderable Part Number |
|------------------|--------------|---------------|----------|-----------------------|
| | | Form | Quantity | |
| IRG7PH42UD1MPbF | TO-247AD | Tube | 25 | IRG7PH42UD1MPbF |

Absolute Maximum Ratings

| Parameter | Parameter | Max. | Units |
|---|--|-----------------------------------|-------|
| V _{CES} | Collector-to-Emitter Voltage | 1200 | V |
| V _{(BR) Transient} | Repetitive Transient Collector-to-Emitter Voltage ② | 1300 | |
| I _C @ T _C = 25°C | Continuous Collector Current | 85 ③ | A |
| I _C @ T _C = 100°C | Continuous Collector Current | 45 | |
| I _{CM} | Pulse Collector Current, V _{GE} =15V ②③ | 200 | |
| I _{LM} | Clamped Inductive Load Current, V _{GE} =20V ① | 120 | |
| I _F @ T _C = 25°C | Diode Continuous Forward Current | 70 | |
| I _F @ T _C = 100°C | Diode Continuous Forward Current | 35 | |
| I _{FRM} | Diode Repetitive Peak Forward Current ② | 120 | |
| V _{GE} | Continuous Gate-to-Emitter Voltage | ±30 | V |
| P _D @ T _C = 25°C | Maximum Power Dissipation | 313 | W |
| P _D @ T _C = 100°C | Maximum Power Dissipation | 125 | |
| T _J T _{STG} | Operating Junction and Storage Temperature Range | -55 to +150 | °C |
| | Soldering Temperature, for 10 sec. | 300 (0.063 in. (1.6mm) from case) | |
| | Mounting Torque, 6-32 or M3 Screw | 10 lbf-in (1.1 N·m) | |

Thermal Resistance

| Parameter | Parameter | Min. | Typ. | Max. | Units |
|--------------------------|--|------|------|------|-------|
| R _{θJC} (IGBT) | Thermal Resistance Junction-to-Case-(each IGBT) ④ | — | — | 0.4 | °C/W |
| R _{θJC} (Diode) | Thermal Resistance Junction-to-Case-(each Diode) ④ | — | — | 1.05 | |
| R _{θCS} | Thermal Resistance, Case-to-Sink (flat, greased surface) | — | 0.24 | — | |
| R _{θJA} | Thermal Resistance, Junction-to-Ambient (typical socket mount) | — | 40 | — | |

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|---------------------------------|---|------|------|-----------|---------------|--|
| $V_{(BR)CES}$ | Collector-to-Emitter Breakdown Voltage | 1200 | — | — | V | $V_{GE} = 0V, I_C = 100\mu\text{A}$ ③ |
| $\Delta V_{(BR)CES}/\Delta T_J$ | Temperature Coeff. of Breakdown Voltage | — | 1.2 | — | V/°C | $V_{GE} = 0V, I_C = 2.0\text{mA}$ (25°C-150°C) |
| $V_{CE(on)}$ | Collector-to-Emitter Saturation Voltage | — | 1.7 | 2.0 | V | $I_C = 30A, V_{GE} = 15V, T_J = 25^\circ\text{C}$ |
| | | — | 2.0 | — | | $I_C = 30A, V_{GE} = 15V, T_J = 150^\circ\text{C}$ |
| $V_{GE(th)}$ | Gate Threshold Voltage | 3.0 | — | 6.0 | V | $V_{CE} = V_{GE}, I_C = 1.0\text{mA}$ |
| g_{fe} | Forward Transconductance | — | 32 | — | S | $V_{CE} = 50V, I_C = 30A, PW = 80\mu\text{s}$ |
| I_{CES} | Collector-to-Emitter Leakage Current | — | 1.0 | 100 | μA | $V_{GE} = 0V, V_{CE} = 1200V$ |
| | | — | 230 | — | | $V_{GE} = 0V, V_{CE} = 1200V, T_J = 150^\circ\text{C}$ |
| V_{FM} | Diode Forward Voltage Drop | — | 1.15 | 1.30 | V | $I_F = 30A$ |
| | | — | 1.10 | — | | $I_F = 30A, T_J = 150^\circ\text{C}$ |
| I_{GES} | Gate-to-Emitter Leakage Current | — | — | ± 100 | nA | $V_{GE} = \pm 30V$ |

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|--------------|------------------------------------|-------------|------|------|---------------|---|
| Q_g | Total Gate Charge (turn-on) | — | 180 | 270 | nC | $I_C = 30A$ $V_{GE} = 15V$ $V_{CC} = 600V$ |
| Q_{ge} | Gate-to-Emitter Charge (turn-on) | — | 24 | 36 | | |
| Q_{gc} | Gate-to-Collector Charge (turn-on) | — | 70 | 110 | | |
| E_{off} | Turn-Off Switching Loss | — | 1210 | 1450 | μJ | $I_C = 30A, V_{CC} = 600V, V_{GE} = 15V$ $R_G = 10\Omega, L = 200\mu\text{H}, T_J = 25^\circ\text{C}$ Energy losses include tail |
| $t_{d(off)}$ | Turn-Off delay time | — | 270 | 290 | ns | $I_C = 30A, V_{CC} = 600V, V_{GE} = 15V$ $R_G = 10\Omega, L = 200\mu\text{H}, T_J = 25^\circ\text{C}$ |
| t_f | Fall time | — | 35 | 43 | | |
| E_{off} | Turn-Off Switching Loss | — | 1936 | — | μJ | $I_C = 30A, V_{CC} = 600V, V_{GE} = 15V$ $R_G = 10\Omega, L = 200\mu\text{H}, T_J = 150^\circ\text{C}$ Energy losses include tail |
| $t_{d(off)}$ | Turn-Off delay time | — | 300 | — | ns | $I_C = 30A, V_{CC} = 600V, V_{GE} = 15V$ $R_G = 10\Omega, L = 200\mu\text{H}, T_J = 150^\circ\text{C}$ |
| t_f | Fall time | — | 160 | — | | |
| C_{ies} | Input Capacitance | — | 3390 | — | pF | $V_{GE} = 0V$ $V_{CC} = 30V$ $f = 1.0\text{MHz}$ |
| C_{oes} | Output Capacitance | — | 130 | — | | |
| C_{res} | Reverse Transfer Capacitance | — | 83 | — | | |
| RBSOA | Reverse Bias Safe Operating Area | FULL SQUARE | | | | $T_J = 150^\circ\text{C}, I_C = 120A$ $V_{CC} = 960V, V_p = 1200V$ $R_g = 10\Omega, V_{GE} = +20V \text{ to } 0V$ |

Notes:

- ① $V_{CC} = 80\% (V_{CES}), V_{GE} = 20V, L = 22\mu\text{H}, R_G = 10\Omega$.
- ② Pulse width limited by max. junction temperature.
- ③ Refer to AN-1086 for guidelines for measuring $V_{(BR)CES}$ safely.
- ④ R_θ is measured at T_J of approximately 90°C .
- ⑤ Calculated continuous current based on maximum allowable junction temperature. Bond wire current limit is 78A. Note that current limitations arising from heating of the device leads may occur with some lead mounting arrangements.
- ⑥ FBSOA operating conditions only
- ⑦ $V_{GE} = 0V, T_J = 75^\circ\text{C}, PW \leq 10\mu\text{s}$.

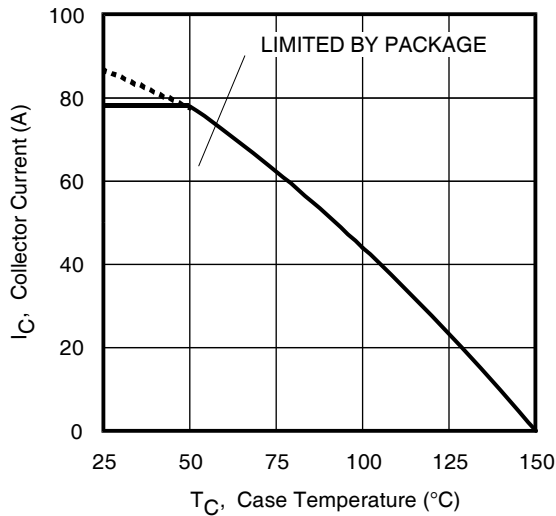


Fig. 1 - Maximum DC Collector Current vs. Case Temperature

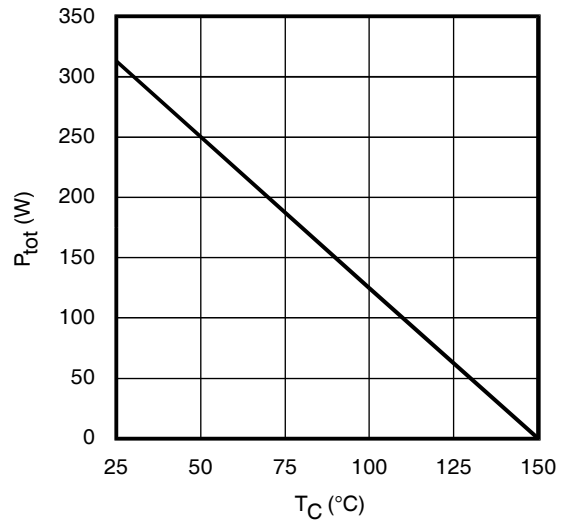


Fig. 2 - Power Dissipation vs. Case Temperature

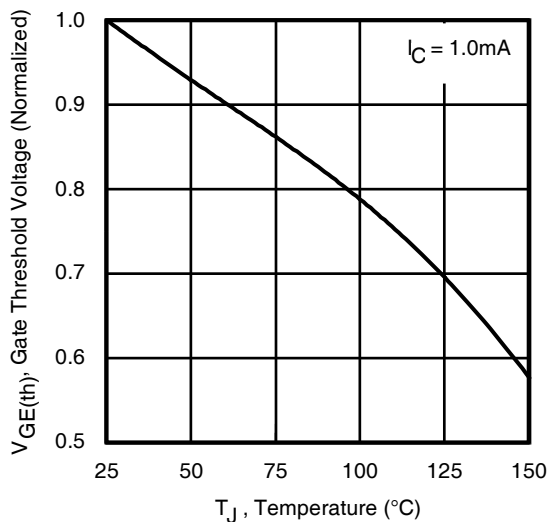


Fig. 3 - Typical Gate Threshold Voltage (Normalized) vs. Junction Temperature

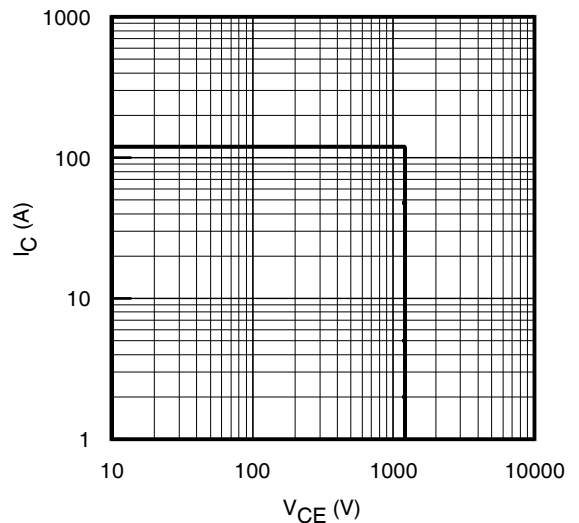


Fig. 4 - Reverse Bias SOA
 $T_J = 150^{\circ}\text{C}; V_{GE} = 20\text{V}$

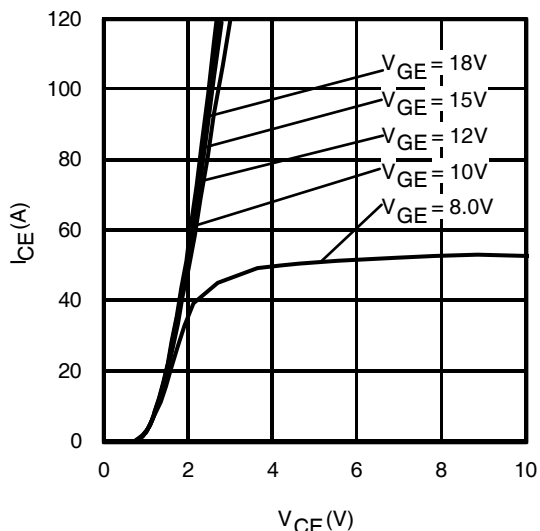


Fig. 5 - Typ. IGBT Output Characteristics
 $T_J = -40^{\circ}\text{C}; t_p = 80\mu\text{s}$

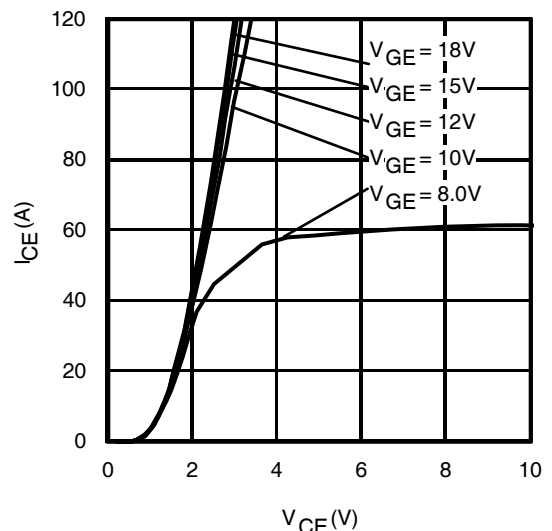


Fig. 6 - Typ. IGBT Output Characteristics
 $T_J = 25^{\circ}\text{C}; t_p = 80\mu\text{s}$

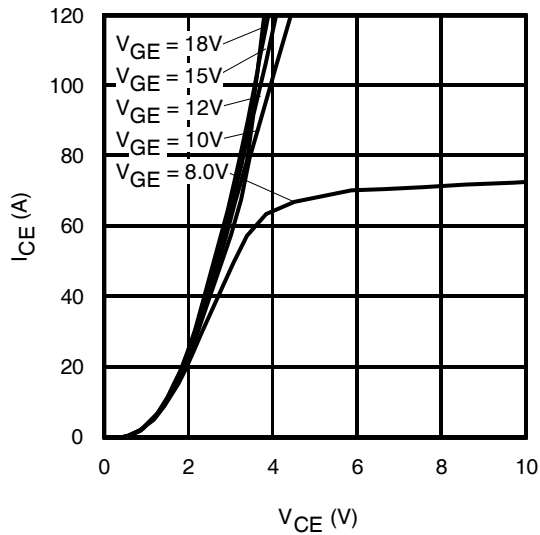


Fig. 7 - Typ. IGBT Output Characteristics
 $T_J = 150^\circ\text{C}$; $t_p = 80\mu\text{s}$

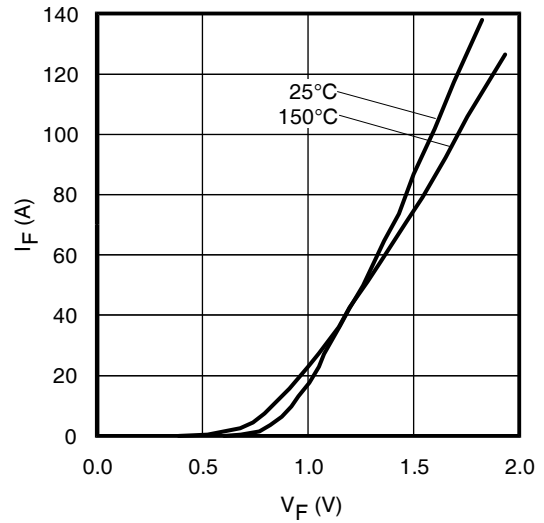


Fig. 8 - Typ. Diode Forward Voltage Drop Characteristics

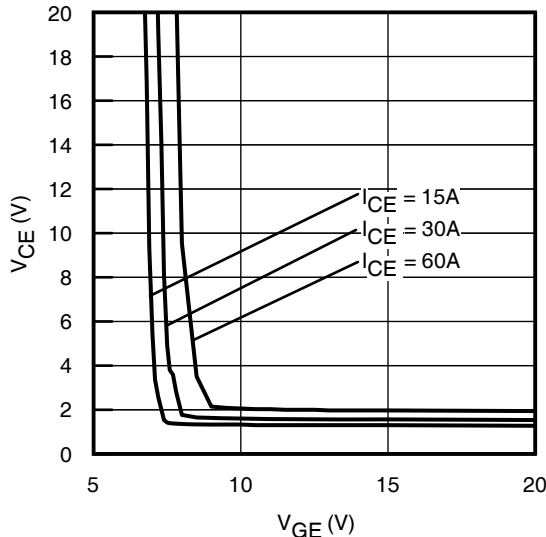


Fig. 9 - Typical V_{CE} vs. V_{GE}
 $T_J = -40^\circ\text{C}$

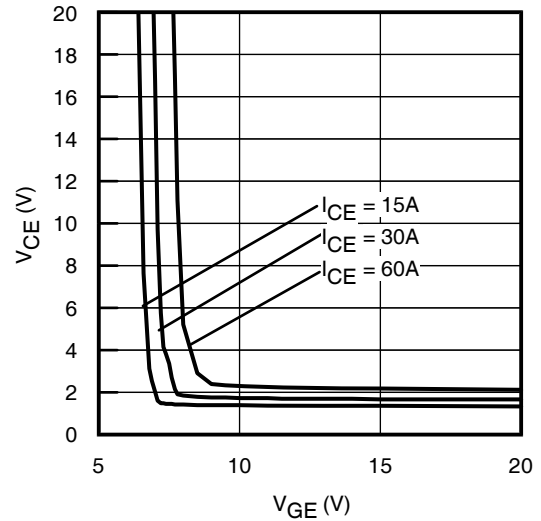


Fig. 10 - Typical V_{CE} vs. V_{GE}
 $T_J = 25^\circ\text{C}$

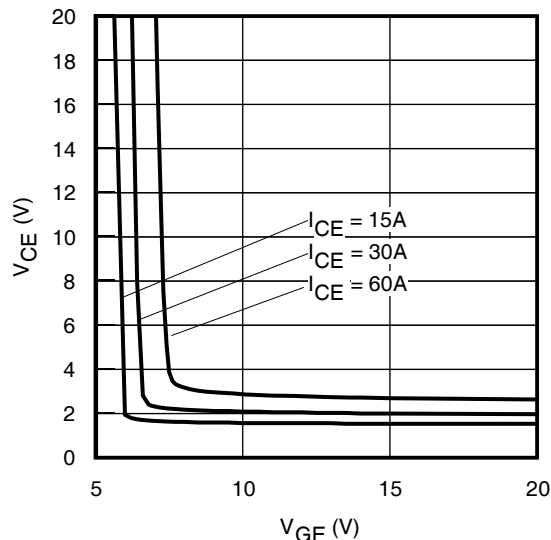


Fig. 11 - Typical V_{CE} vs. V_{GE}
 $T_J = 150^\circ\text{C}$

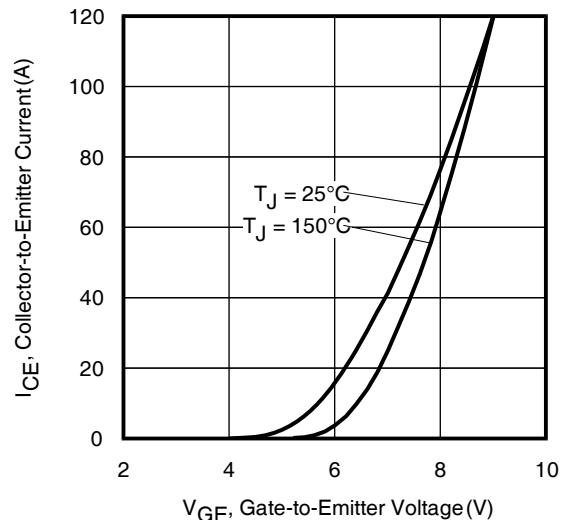
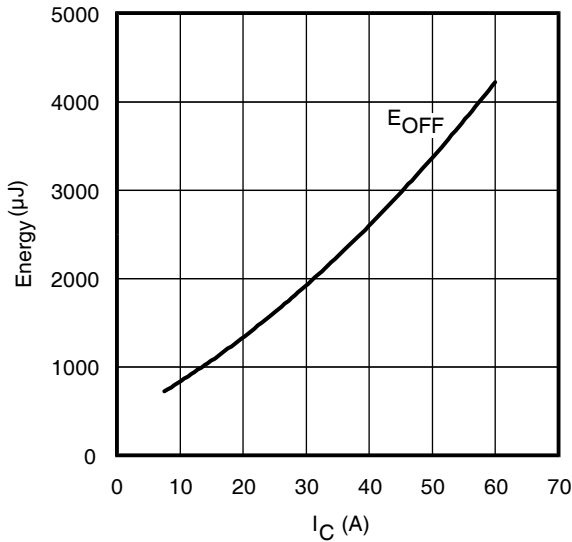
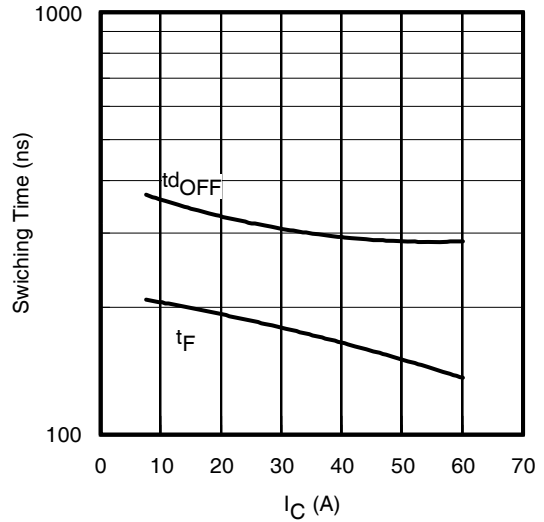
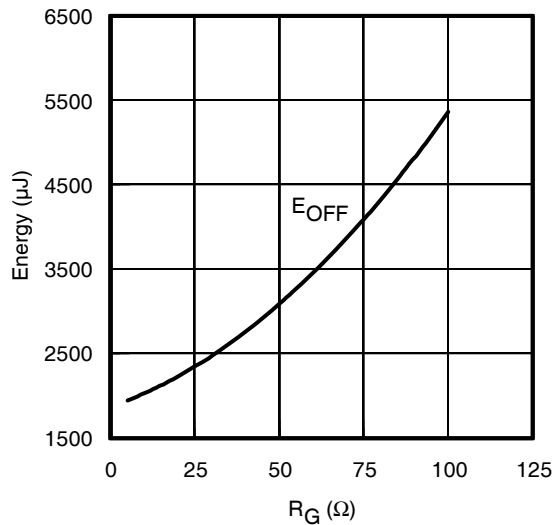
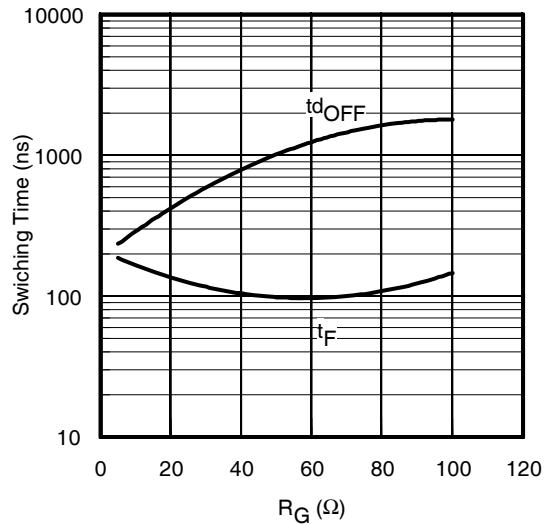
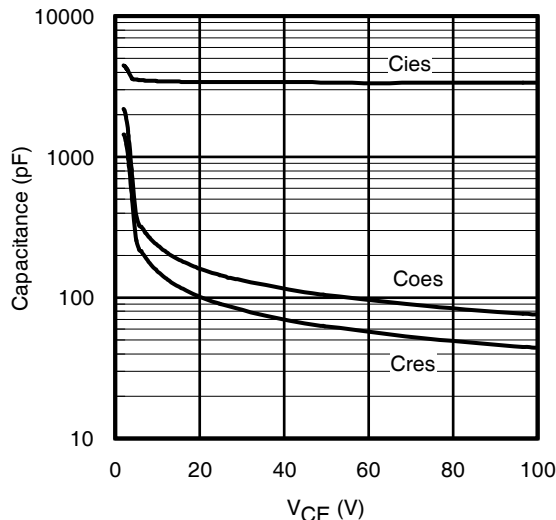
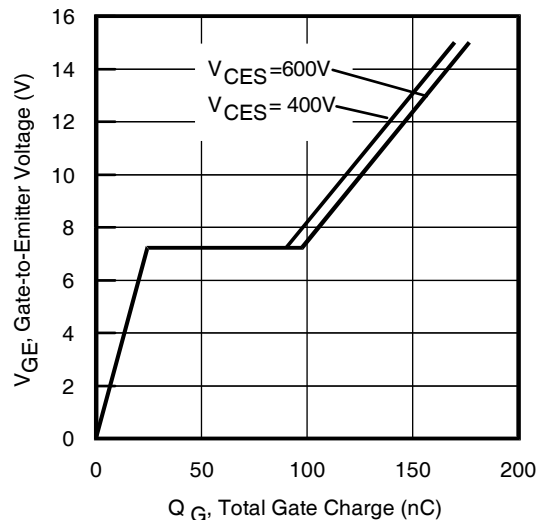
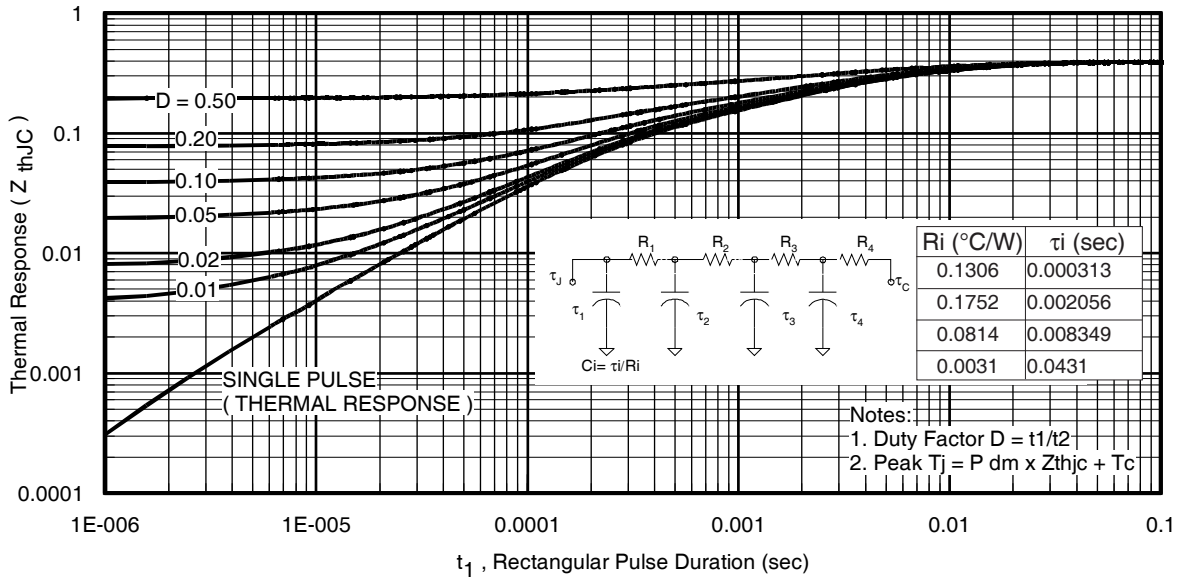
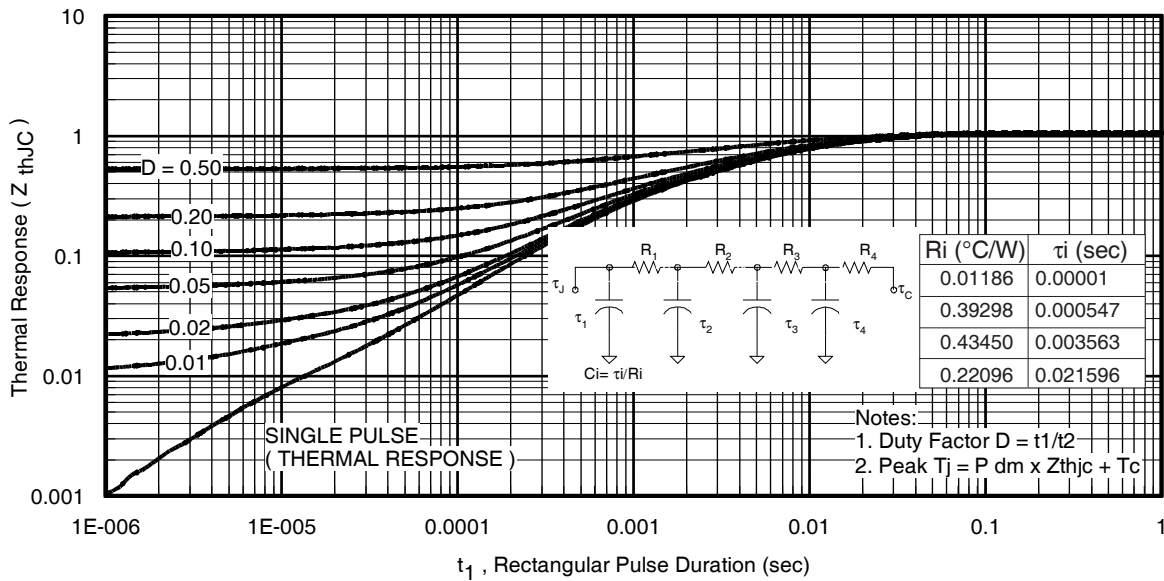
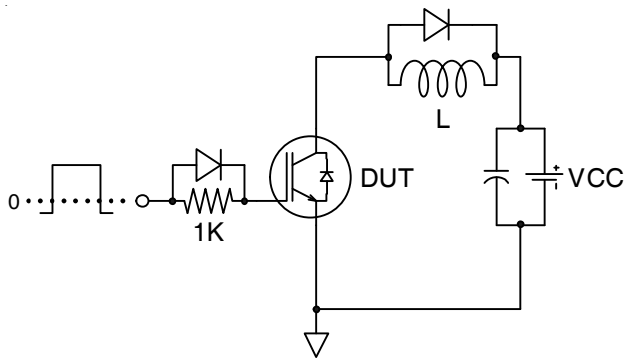
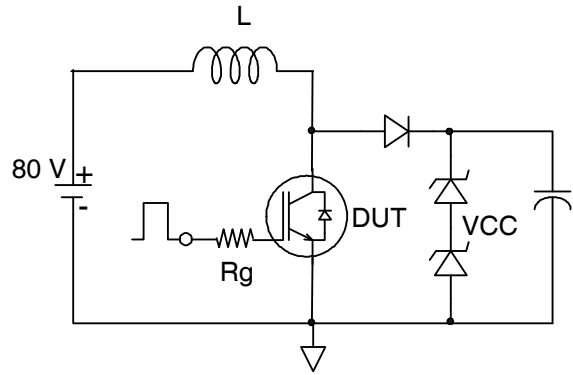
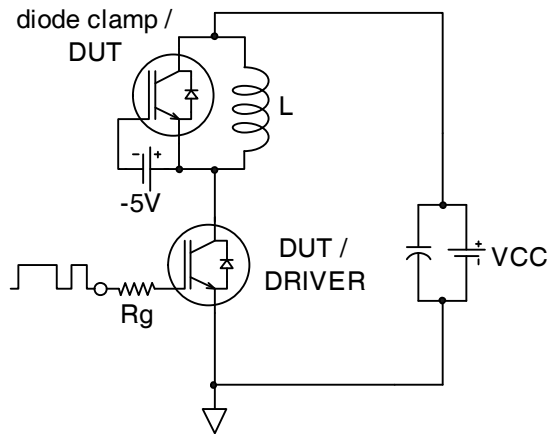
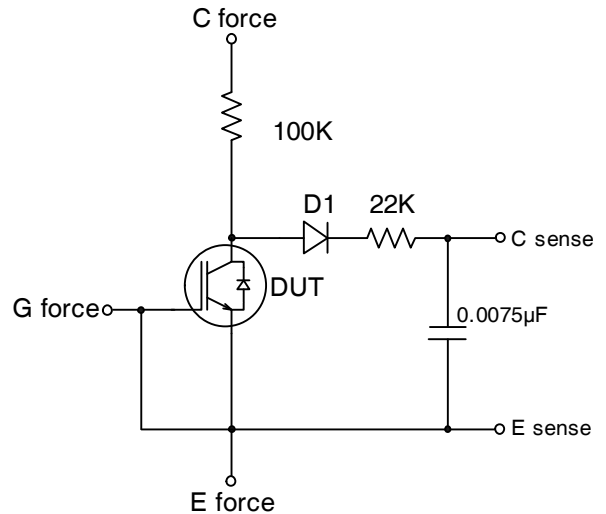
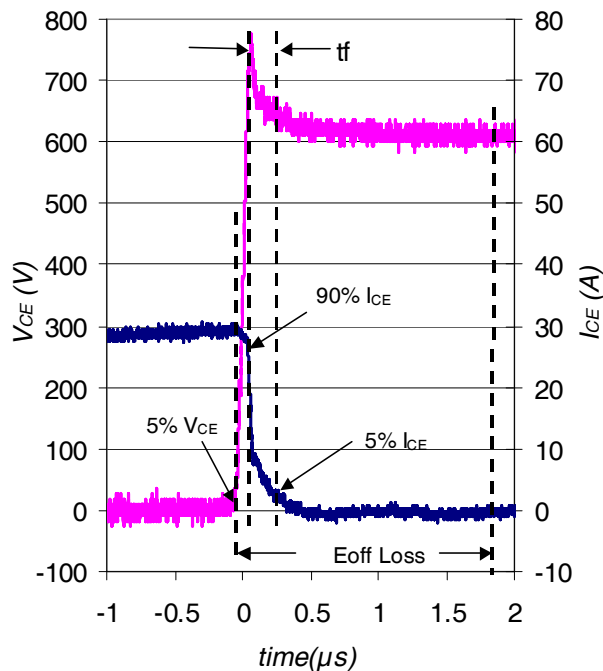
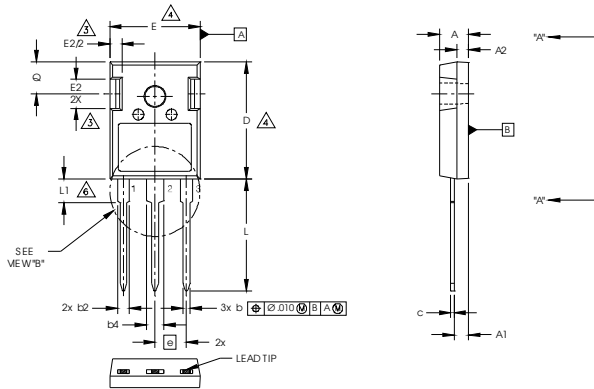


Fig. 12 - Typ. Transfer Characteristics
 $V_{CE} = 50\text{V}$; $t_p = 10\mu\text{s}$


Fig. 13 - Typ. Energy Loss vs. I_C
 $T_J = 150^\circ\text{C}; L = 200\mu\text{H}; V_{CE} = 600\text{V}; R_G = 10\Omega; V_{GE} = 15\text{V}$

Fig. 14 - Typ. Switching Time vs. I_C
 $T_J = 150^\circ\text{C}; L = 200\mu\text{H}; V_{CE} = 600\text{V}; R_G = 10\Omega; V_{GE} = 15\text{V}$

Fig. 15 - Typ. Energy Loss vs. R_G
 $T_J = 150^\circ\text{C}; L = 200\mu\text{H}; V_{CE} = 600\text{V}; I_{CE} = 30\text{A}; V_{GE} = 15\text{V}$

Fig. 16 - Typ. Switching Time vs. R_G
 $T_J = 150^\circ\text{C}; L = 200\mu\text{H}; V_{CE} = 600\text{V}; I_{CE} = 30\text{A}; V_{GE} = 15\text{V}$

Fig. 17 - Typ. Capacitance vs. V_{CE}
 $V_{GE} = 0\text{V}; f = 1\text{MHz}$

Fig. 18 - Typical Gate Charge vs. V_{GE}
 $I_{CE} = 30\text{A}; L = 680\mu\text{H}$


Fig. 19. Maximum Transient Thermal Impedance, Junction-to-Case (IGBT)

Fig. 20. Maximum Transient Thermal Impedance, Junction-to-Case (DIODE)


Fig.C.T.1 - Gate Charge Circuit (turn-off)

Fig.C.T.2 - RBSOA Circuit

Fig.C.T.3 - Switching Loss Circuit

Fig.C.T.4 - BVCES Filter Circuit

Fig. WF1 - Typ. Turn-off Loss Waveform
 @ $T_J = 150^\circ\text{C}$ using Fig. CT.3

TO-247AD Package Outline (Dimensions are shown in millimeters (inches))


| SYMBOL | DIMENSIONS | | | | NOTES |
|--------|--------------|------|--------------|-------|-------|
| | INCHES | | MILLIMETERS | | |
| | MIN. | MAX. | MIN. | MAX. | |
| A | .190 | .204 | 4.83 | 5.20 | |
| A1 | .090 | .100 | 2.29 | 2.54 | |
| A2 | .075 | .085 | 1.91 | 2.16 | |
| b | .042 | .052 | 1.07 | 1.33 | |
| b2 | .075 | .094 | 1.91 | 2.41 | |
| b4 | .113 | .133 | 2.87 | 3.38 | |
| c | .022 | .026 | 0.55 | 0.68 | |
| D | .819 | .830 | 20.80 | 21.10 | 4 |
| D1 | .640 | .694 | 16.25 | 17.65 | 5 |
| E | .620 | .635 | 15.75 | 16.13 | 4 |
| E1 | .512 | .570 | 13.00 | 14.50 | |
| E2 | .145 | .196 | 3.68 | 5.00 | |
| e | .215 Typical | | 5.45 Typical | | |
| L | .780 | .800 | 19.80 | 20.32 | |
| L1 | .161 | .173 | 4.10 | 4.40 | |
| ∅ P | .138 | .143 | 3.51 | 3.65 | |
| Q | .216 | .236 | 5.49 | 6.00 | |
| S | .238 | .248 | 6.04 | 6.30 | |

LEAD ASSIGNMENTS
HEXFET

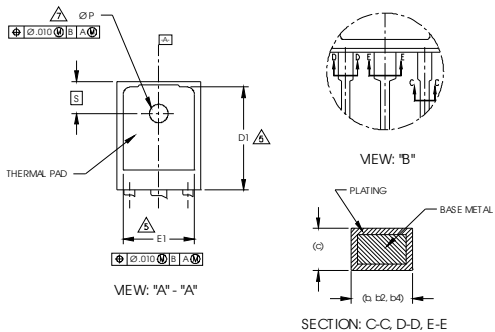
- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

IGBTs, CoPACK

- 1.- GATE
- 2.- COLLECTOR
- 3.- EMITTER
- 4.- COLLECTOR

DIODES

- 1.- ANODE/OPEN
- 2.- CATHODE
- 3.- ANODE

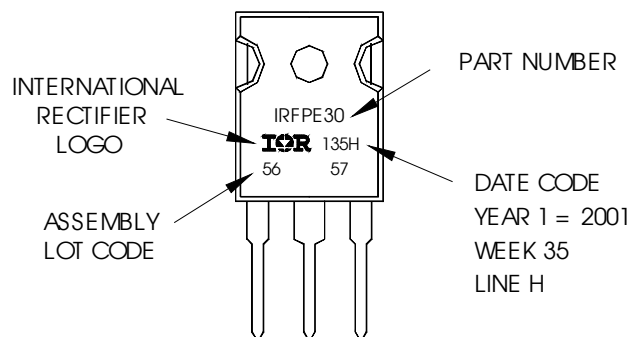

NOTES:

- 1 DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M 1994.
- 2 DIMENSIONS ARE SHOWN IN INCHES AND MILLIMETERS.
- 3 CONTOUR OF SLOT OPTIONAL.
- 4 DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 5 THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS D1 & E1.
- 6 LEAD FINISH UNCONTROLLED IN L1.
- 7 ∅ P TO HAVE A MAXIMUM DRAFT ANGLE OF 1.5 ° TO THE TOP OF THE PART WITH A MAXIMUM HOLE DIAMETER OF .154 INCH.

TO-247AD Part Marking Information

EXAMPLE: THIS IS AN IRFPE30
WITH ASSEMBLY
LOT CODE 5657
ASSEMBLED ON WW 35, 2001
IN THE ASSEMBLY LINE "H"

Note: "P" in assembly line position
indicates "Lead-Free"



TO-247AD package is not recommended for Surface Mount Application.

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

Qualification information[†]

| | | |
|----------------------------|---|-----|
| Qualification level | Industrial [†] (per JEDEC JESD47F) ^{††} | |
| Moisture Sensitivity Level | TO-247AD | N/A |
| RoHS compliant | Yes | |

† Qualification standards can be found at International Rectifier's web site

<http://www.irf.com/product-info/reliability>

†† Applicable version of JEDEC standard at the time of product release.

Revision History

| Date | Comments |
|-----------|---|
| 4/25/2013 | Corrected part number from "IRG7PH42UD1M" to "IRG7PH42UD1MPbF". |

Data and specifications subject to change without notice.

International
 Rectifier

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TAC Fax: (310) 252-7903

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[GT50JR22\(STA1ES\)](#) [TIG058E8-TL-H](#) [IGW40N120H3FKSA1](#) [VS-CPV364M4KPBF](#) [NGTB25N120FL2WAG](#) [NGTG40N120FL2WG](#)
[RJH60F3DPQ-A0#T0](#) [APT40GR120B2SCD10](#) [APT15GT120BRG](#) [APT20GT60BRG](#) [NGTB75N65FL2WAG](#) [NGTG15N120FL2WG](#)
[IXA30RG1200DHGLB](#) [IXA40RG1200DHGLB](#) [APT70GR65B2DU40](#) [NTE3320](#) [QP12W05S-37A](#) [IHF40N65R5SXXSA1](#) [APT70GR120J](#)
[APT35GP120JDQ2](#) [XD15H120CX1](#) [XD25H120CX0](#) [XP15PJS120CL1B1](#) [IGW30N60H3FKSA1](#) [STGWA8M120DF3](#) [IGW08T120FKSA1](#)
[IGW75N60H3FKSA1](#) [FGH60N60SMD_F085](#) [FGH75T65UPD](#) [STGWA15H120F2](#) [IKA10N60TXKSA1](#) [IHW20N120R5XKSA1](#)
[RJH60D2DPP-M0#T2](#) [IKP20N60TXKSA1](#) [IHW20N65R5XKSA1](#) [APT70GR120JD60](#) [AOD5B60D](#) [APT70GR120L](#) [STGWT60H65FB](#)
[STGWT60H65DFB](#) [STGWT40V60DF](#) [STGWT20V60DF](#) [STGB10NB37LZT4](#)